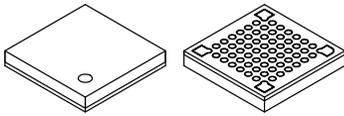


MECHANICAL CASE OUTLINE

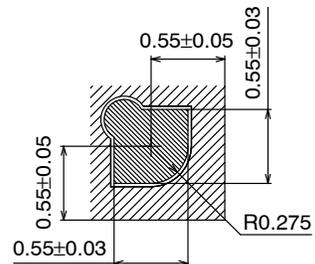
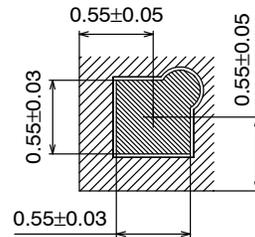
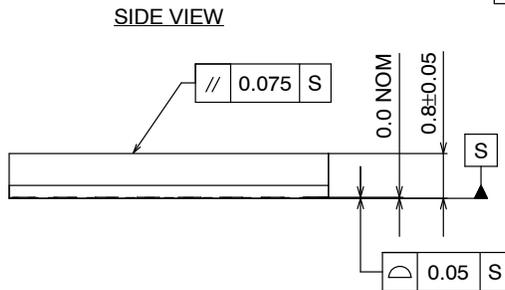
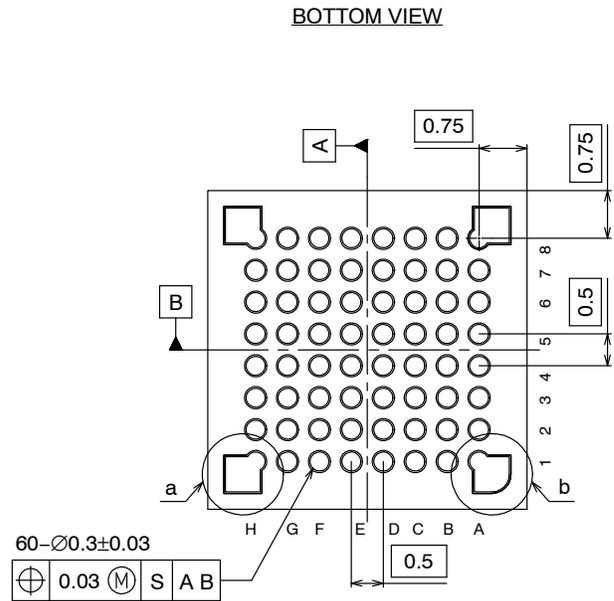
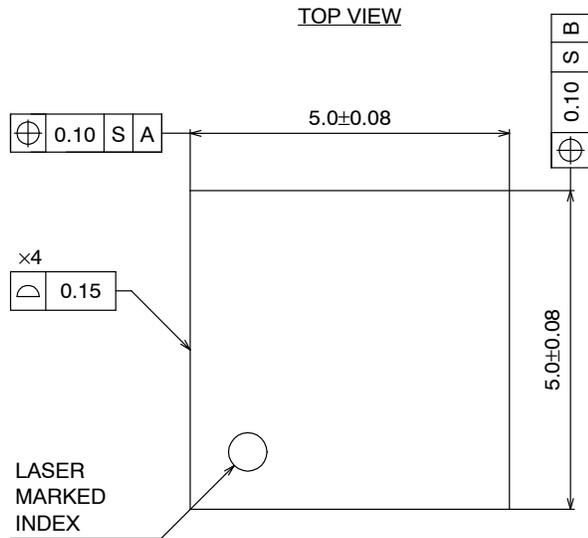
PACKAGE DIMENSIONS

ON Semiconductor®

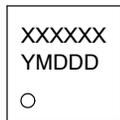


LFLGA64 5x5 / FLGA64
CASE 569AD
ISSUE A

DATE 17 JAN 2014



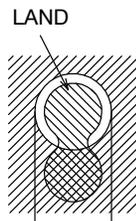
GENERIC MARKING DIAGRAM*



XXXXXX = Specific Device Code
Y = Year
M = Month
DDD = Additional Traceability Data

*This information is generic. Please refer to device data sheet for actual part marking.
Pb-Free indicator, "G" or microdot "▪", may or may not be present.

NSMD
Off set Via type

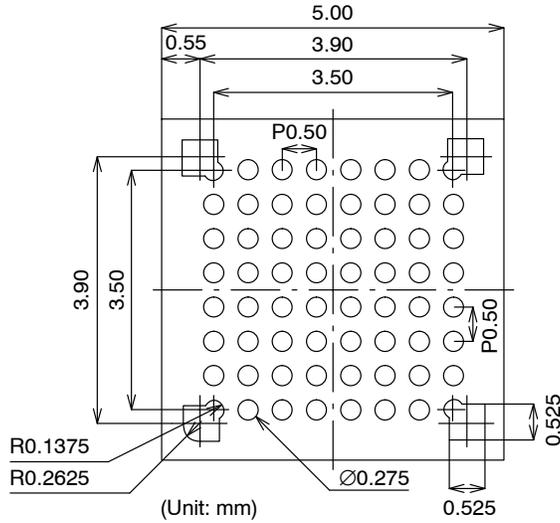


DOCUMENT NUMBER:	98AON67021E	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	LFLGA64 5X5 / FLGA64	PAGE 1 OF 3

LFLGA64 5x5 / FLGA64
CASE 569AD
ISSUE A

DATE 17 JAN 2014

SOLDERING FOOTPRINT*



NOTE: The measurements are not to guarantee but for reference only.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

DOCUMENT NUMBER:	98AON67021E	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	LFLGA64 5X5 / FLGA64	PAGE 2 OF 3

